IN THE CLAIMS

Please replace the claims as filed with the claims set forth below. This listing of claims will replace all prior versions, and listings, of claims in the application:

1-5. (Cancelled)

- 6. (currently amended) A process for the preparation of a dispersion according to claim 1. comprising the steps of:
 - (a) preparing an intrinsically conductive polymer from monomers, wherein the temperature during the polymerization is controlled such that it does not exceed a value of more than 5°C over the starting temperature,
 - (b) triturating and/or dispersing the product from step (a) in the presence of a nonelectrically conductive, non-polymeric polar substance which is inert vis-à-vis the conductive polymer, applying adequate shearing forces, wherein the weight ratio between the conductive polymer and the polar substance is 2:1 to 1:10, and
 - (c) dispersing the product from step (b) in a dispersant, wherein the weight ratio between the conductive polymer and the dispersant is less than 1:10 and wherein the resulting dispersion contains particles of at least one intrinsically conductive polymer.

 wherein the particle size is on average (weight) less than 1 μm, characterized in that the dispersant is a liquid at room temperature, and a layer, film or sheet formed from this dispersion has a conductivity of >100 S/cm after removal of the dispersant.
- 7. (previously presented) The process according to claim 6, characterized in that at no time during the polymerization is the rate of the temperature rise during step (a) more than 1 K/minute.

- 8. (previously presented) The process according to claim 7, characterized in that in step (b) furthermore at least one non-conductive polymer is present.
- 9. (previously presented) The process according to claim 8, characterized in that the non-conductive polymer is a thermoplastic polymer.
- 10. (previously presented) The process according to claim 6, characterized in that the product from step (b) is subjected to a post-treatment.
- 11. (previously presented) The process according to claim 10, characterized in that the portion of the polar substance or of the non-conductive polymer in the product from step (b) is reduced during the post-treatment by washing or extraction.
- 12. (previously presented) The process according to claim 6, characterized in that solvents and/or auxiliaries are added which support the subsequent dispersion step (c).
- 13. (previously presented) The process according to claim 6, characterized in that the product from step (c) is subjected to a post-treatment.
- 14. (previously presented) The process according to claim 6, characterized in that viscosity regulators, wetting aids, matrix polymers, stabilizers, cross-linking auxiliaries, evaporation regulators and/or other auxiliaries and additives which support an optionally following shaping process are added.
- 15. (previously presented) The process according to claim 14, characterized in that the addition takes place before or during step (c).
- 16. (previously presented) The process according to claim 6, characterized in that during the post-treatment of the product of step (b) and/or during dispersion step (c) an organic solvent is used which has a surface tension of more than 25 mN/m.

- 17. (previously presented) The process according to claim 10, characterized in that the concentration of the conductive polymer increases during the post-treatment of the product from step (b) by at least 5 wt.-%, relative to the constituents solid at room temperature.
- 18. (previously presented) The process according to claim 6, characterized in that the dispersion step(s) is or are carried out in a dispersion device selected from the grouping consisting of a ball mill, a bead mill, a three-roll mill and a high-pressure dispersion device.
- 19. (previously presented) The process according to claim 6, characterized in that the dispersion is carried out under ultrasound.

20-21. (Cancelled)

- 22. (previously presented) The use of a dispersion prepared according to the process of claim 6 for the preparation of mouldings, self-supporting films or coatings with electric conductivity.
- 23. (previously presented) The use according to claim 22 characterized in that the mouldings, self-supporting films or coatings are electrodes, antennae, polymeric electronics components, capacitors and double-layer capacitors (DLC).